


- ① Substrate: 0.0625"±0.007" FR4/G10 or equivalent high temp material. 1/2 oz. Cu clad. SnPb plating
- ② Pins: Material- Brass Alloy 360 1/2 hard; finish- 10μ" Au over 50μ" Ni (min.)
- ③ Pins: shell material- Brass Alloy 360 1/2 hard; finish- 10μ" Au over 50μ" Ni (min.). Contact material- BeCu; finish 10μ" Au over 100μ" Ni (min.)
- ④ Leads: material- BeCu Alloy 194; plating- 60/40 SnPb (150-400μ")

Description: PACKAGE CONVERTER

16 position DIP female sockets to SOIC J lead surface mount foot (0.050" Pitch).

All tolerances: ±0.005" (unless stated otherwise). Materials and specifications are subject to change without notice.

	PC-DIP/SOIC16-04 Drawing	Status: Released	Scale: 3:1	Rev: B
	© 1992 IRONWOOD ELECTRONICS, INC. PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100 www.ironwoodelectronics.com	Drawing by: C. Hautman	Date: 10/12/92	
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